

L12	1909357	(top upper front) near (side or surface) or topside or upperside frontside	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:05
L13	2052185	(top upper front active) near (side or surface) or topside or upperside frontside activeside	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:06
L14	167534	11 with 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:10
L15	312902	11 with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:10
L16	829170	mosfet mos adj fet fet transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:11
L17	2355	14 same 15 same 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 14:11
L18	79	14 same 15 same 16 same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:15
L20	36	18 and (@ad < "19991216")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 14:13

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	3819830	(back or under or below) near (side or surface) or backside or underneath or bottom	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:04
L4	12523	through adj (wafer chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 12:57
L6	597215	through adj hole throughhole through adj hole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:03
L7	183380	mosfet mos adj fet fet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:10
L8	4616	6 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:04
L9	779	6 same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:04
L10	384	6 with 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:04
L11	6351384	terminal electrode source drain gate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:04

L21	239	14 same 15 same 16 near2 (power)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 14:11
L22	98	21 and (@ad < "19991216")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 14:21
L23	707433	(chip or die or dice or ic)	US-PGPUB; USPAT	OR	ON	2005/05/13 14:13
L24	4722000	electrode or contact or pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 14:13
L25	57	(encapsulat\$6 epoxy resin housing packaging)near2 (window or opening or hole) same expos\$4 near2 L24 same L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 14:14
L26	4297766	(encapsulat\$6 epoxy resin housing packaging)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 14:18
L27	47	21 and (@ad < "19991216") and 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 15:20
L29	2761	((438/111) or (438/112) or (438/116) or (438/123) or (438/124) or (438/64)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 15:20
L30	1177	29 and (@ad < "19991216")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 15:20